

IEEE Components, Packaging and Manufacturing Technology Society – OC Chapter

Tuesday, June 25, 2013 Technical Meeting

The Latest Technology Trend of Packaging Materials for Power Devices

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Abstract

In today's mobile devices market, the demand for higher powered consumer products is increasing. As a response to this increase in demand, the importance of thermal management is reaching critical mass. One method of addressing thermal management is found in the encapsulating material for power devices. The encapsulating material would require high heat dissipation and high thermal conductivity. Thermal management is especially important in the application of cutting edge power devices, such as the SiC device, where the junction temperature range has no limitation. In order to push the performance envelope on new devices, enhancement in heat resistance of the surrounding material is highly critical. Suitable constitution of appropriate encapsulation material and its ensuing effects on device reliability will be introduced at this technical meeting.

Biography

After earning a Master's degree in energy material from the Yokohama National University in 1984, he joined the research and development center at Toshiba and was involved in the development of organic material for semiconductor devices. In 1994, he transferred to Toshiba Chemical Corporation. In 2002, the company changed its name to Kyocera Chemical Corporation. At Kyocera Chemical Corporation, Mr. Uchida has been engaged in the development of encapsulation resin used in semiconductor devices.

Date: **Tuesday, June 25, 2013**

Location: **Broadcom Corporation, 5300 California Ave., Irvine, CA 92617 – Bldg. 2 Room 2-1037 Salt Creek**
Check in at the Security Gate and proceed to Bldg. 2. You will be escorted into the building.

Time: **5:30-6:00pm: Social time, 6:00-7:00pm: Presentation, 7:00pm: Dinner (free for attendees!)**

RSVP: **IEEE members and non-members all are welcome. Please RSVP at <http://tinyurl.com/nth44jx>**
Please be at the Bldg. 2 entrance by 6:00 pm; no escorts after that. For questions regarding RSVP, please contact Cristina Nicoara (cnicoara@broadcom.com).

For more information please contact the following officers of the IEEE CPMT OC Chapter:

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